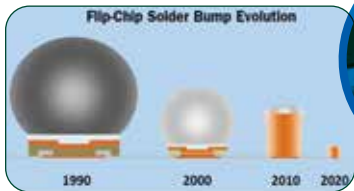


Ultra-Low Residue No-Clean Flip-Chip Flux



- Copper-pillar and standard bump
- Residues compatible with underfill materials
- No delamination and high-mechanical reliability
- Suited for lead-free alloys
- Ultra-low residue levels post-reflow
- Halogen-free
- True no-clean

Contact our engineers: askus@indium.com

Learn more: www.indium.com/flip-chip-fluxes



*All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified.
Indium Corporation is an ISO 9001:2015 registered company.*



Ultra-Low Residue No-Clean Flip-Chip Flux

	NC-699	NC-26-A	NC-26S	NC-809 ★Best in class	Standard No-Clean Flux
Typical post reflow residue weight (TGA data)	<2%	~5%	<10%	<7%	40-60%
Solderability					
Residue level					
Allows easy underfilling with CUF/MUF					
Compatibility with CUF/MUF					
Holds large die in place during reflow					
Use in volume by major OSAT/ODM for thin devices	Memory	Logic	Logic	Logic	

Major Users

- ASIC chip for crypto-currency mining
- Memory
- SAW filter
- Power QFN

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